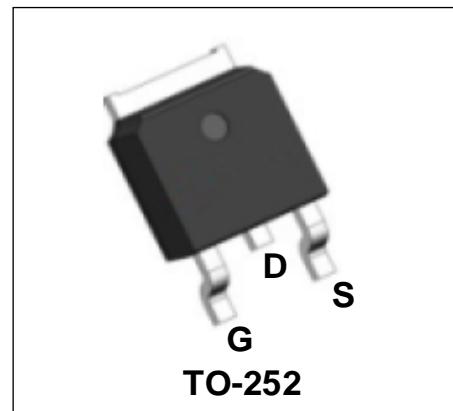


## 150V N-Channel Enhancement Mode Power MOSFET

### Description

WMO28N15T2 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

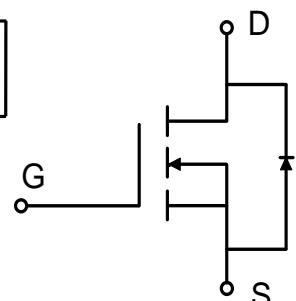


### Features

- $V_{DS} = 150V$ ,  $I_D = 28A$   
 $R_{DS(on)} < 48m\Omega$  @  $V_{GS} = 10V$
- Green Device Available
- Low Gate Charge
- 100% EAS Guaranteed

### Applications

- LED Backlighting
- Synchronous Rectification
- Motor Control



### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	150	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <small><math>T_C = 25^\circ C</math></small>	$T_C = 25^\circ C$	$I_D$	28	A
	$T_C = 100^\circ C$		19.5	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	112	A
Single Pulse Avalanche Energy <sup>2</sup>		$EAS$	20	mJ
Total Power Dissipation	$T_C = 25^\circ C$	$P_D$	73.5	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	64	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.7	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	150	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	3.2	4	V
Drain-Source on-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	-	40	48	$\text{m}\Omega$
Forward Transconductance <sup>4</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 10\text{A}$	-	16.3	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 75\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	512	-	pF
Output Capacitance	$C_{\text{oss}}$		-	75	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	11	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	5.1	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 75\text{V}, I_D = 10\text{A}$	-	12	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	4	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	5.2	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 75\text{V}, R_G = 10\Omega, I_D = 10\text{A}$	-	13.5	-	ns
Rise Time	$t_r$		-	7.8	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	15	-	
Fall Time	$t_f$		-	3.8	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_c = 25^\circ\text{C}$	$I_S$	-	-	28	A

Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.4\text{mH}, I_{\text{AS}}=10\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

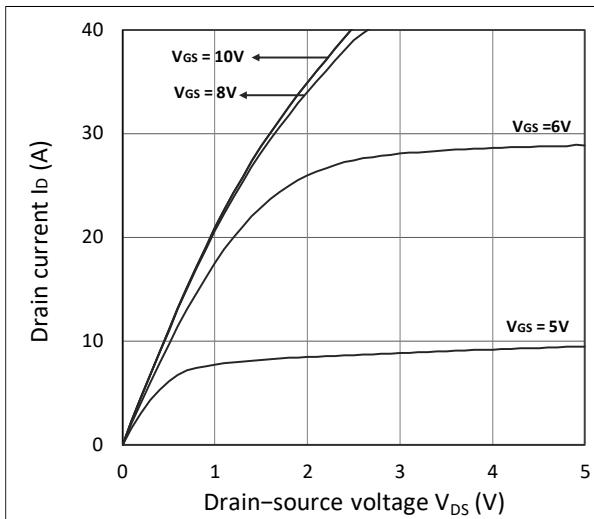


Figure 1. Output Characteristics

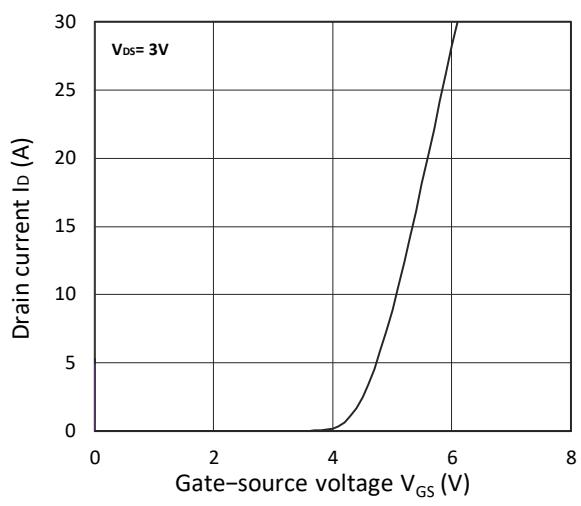


Figure 2. Transfer Characteristics

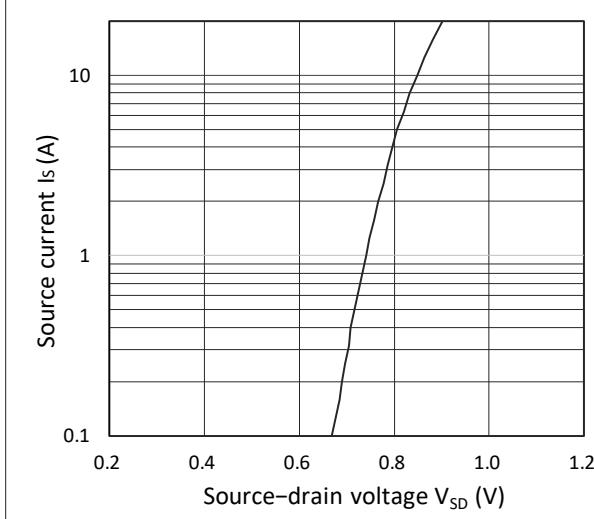
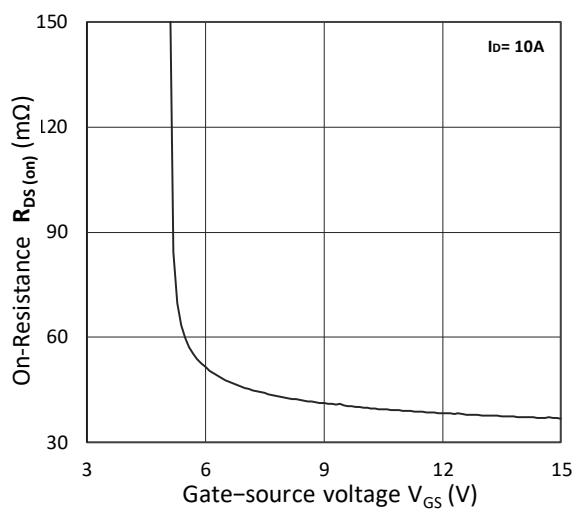
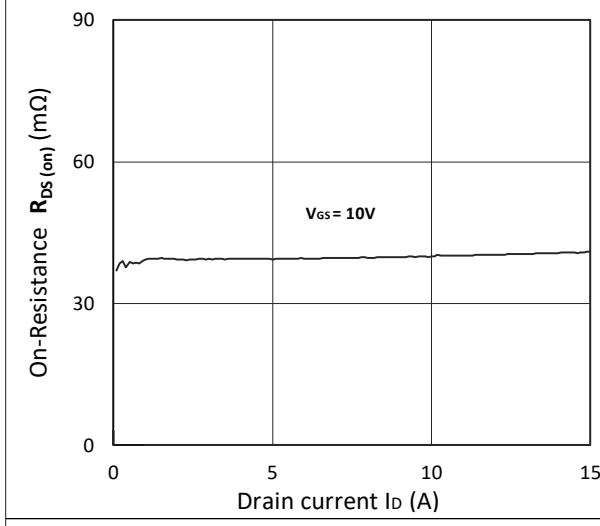
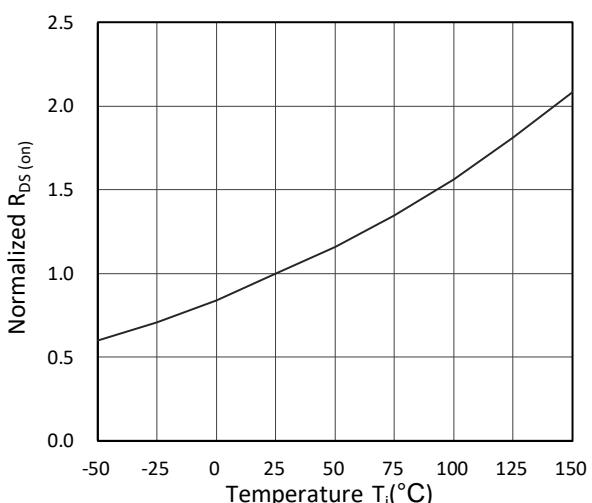


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

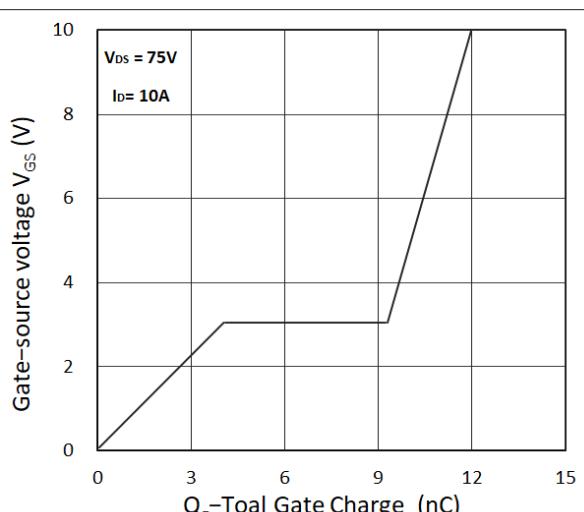
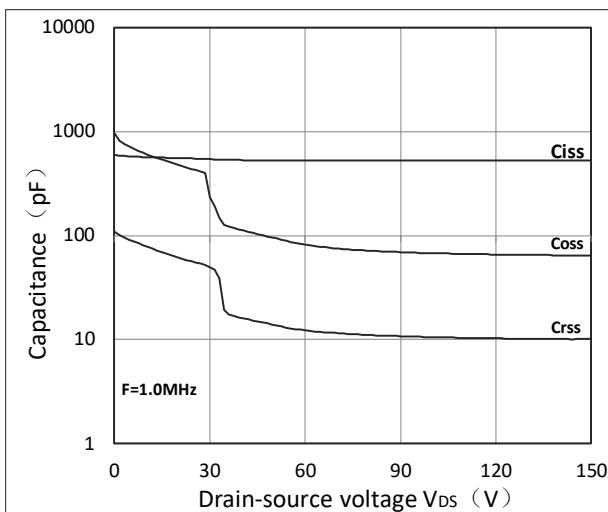


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics

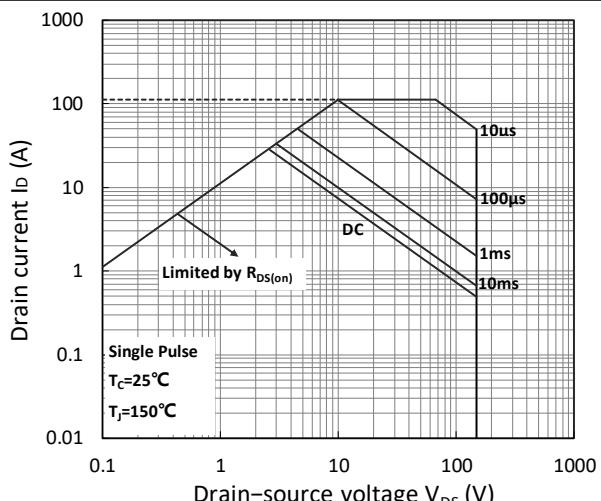
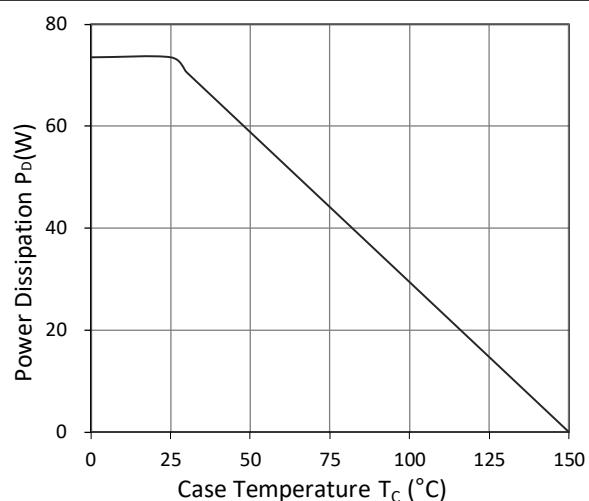


Figure 9. Power Dissipation

Figure10. Safe Operating Area

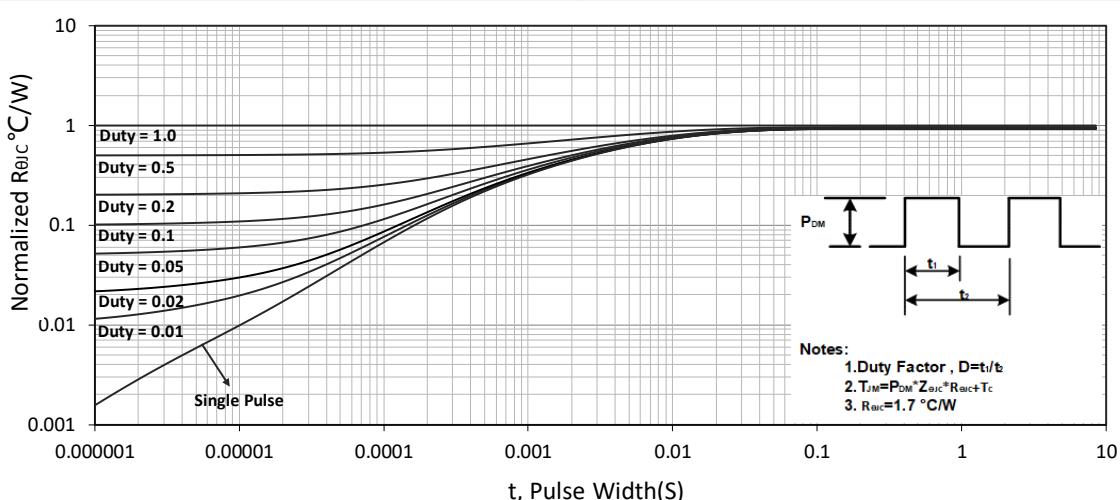
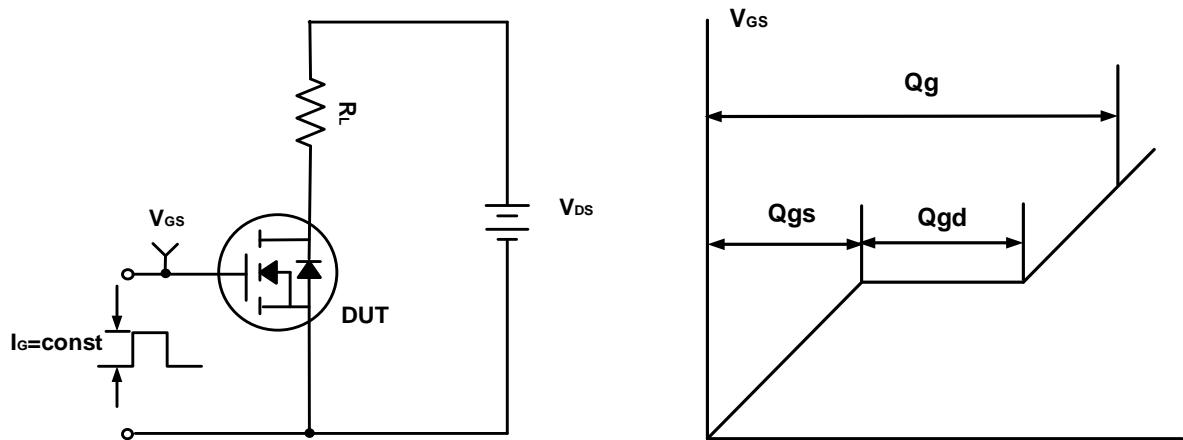
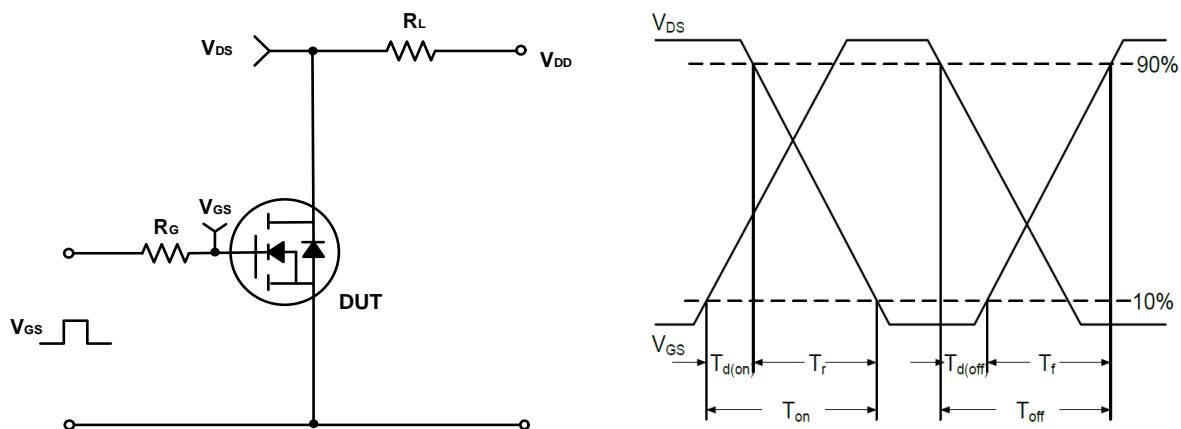
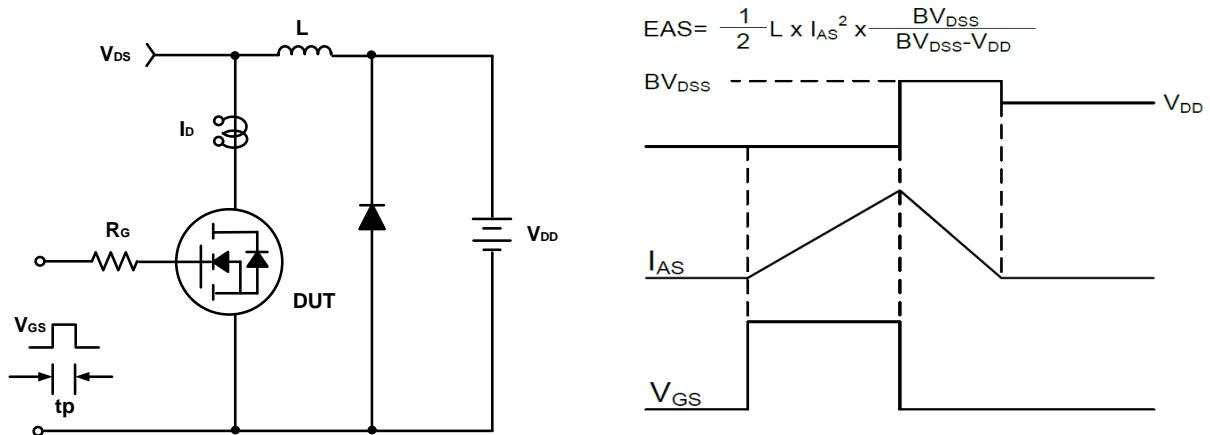
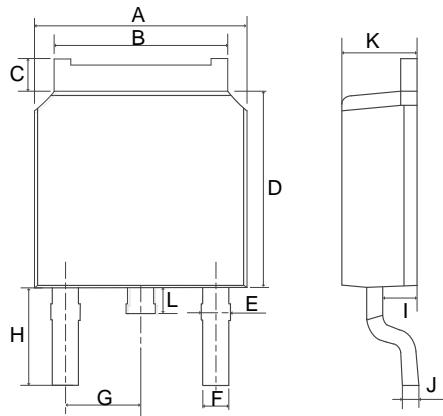


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for TO-252

## COMMON DIMENSIONS

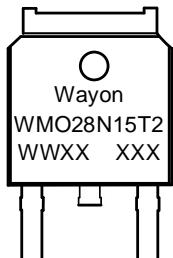


SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
E	0.68	1.10
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00

## Ordering Information

Part	Package	Marking	Packing method
WMO28N15T2	TO-252	WMO28N15T2	Tape and Reel

## Marking Information



WMO28N15T2 = Device code

WWXX XXX= Date code

## Contact Information

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WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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